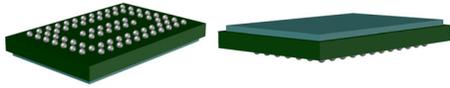
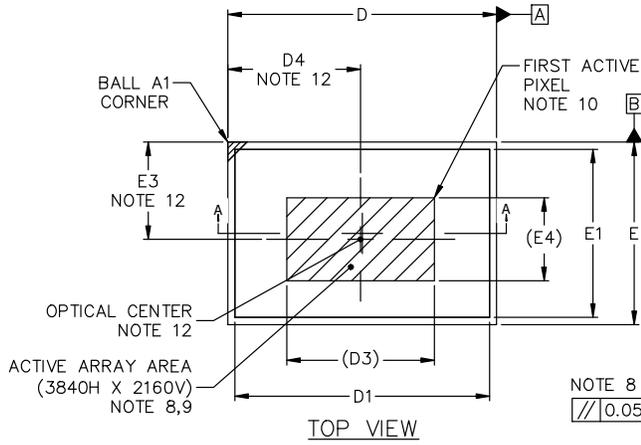


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

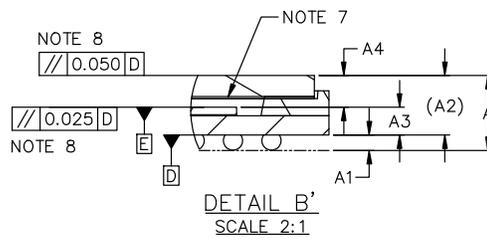
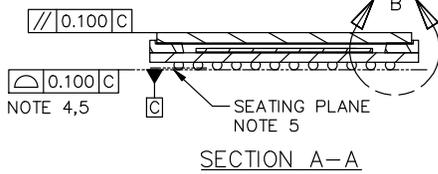


PBGA75 14.00x9.50x1.55, 1.00P
CASE 117CU
ISSUE A

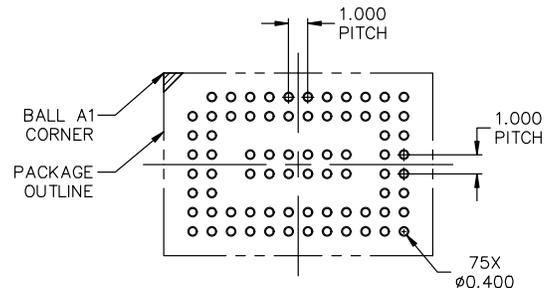
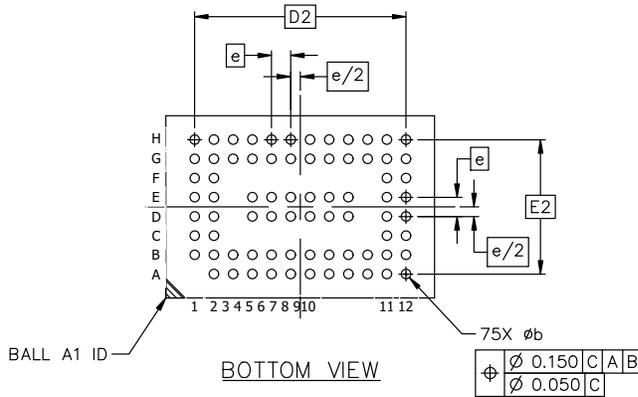
DATE 18 JAN 2024



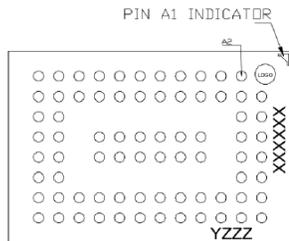
- NOTES:
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
 3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 6. GLASS: 0.550 THICKNESS; REFRACTIVE INDEX = 1.52.
 7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.275 THICKNESS.
 8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
 9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS $\pm 1^\circ$.
 10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
 11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
 12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.087, -0.315).



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	----	----	2.100
A1	0.350	0.400	0.450
A2	1.550 REF.		
A3	0.625	0.725	0.825
A4	0.725	0.825	0.925
b	0.450	0.500	0.550
D	13.900	14.000	14.100
D1	13.146	13.246	13.346
D2	11.000 BSC		
D3	7.680 REF.		
D4	6.813	6.913	7.013
E	9.400	9.500	9.600
E1	8.645	8.745	8.845
E2	7.000 BSC		
E3	4.965	5.065	5.165
E4	4.320 REF.		
e	1.000 BSC		



GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT*
*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	PBGA75 14.00x9.50x1.55, 1.00P	PAGE 1 OF 1

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